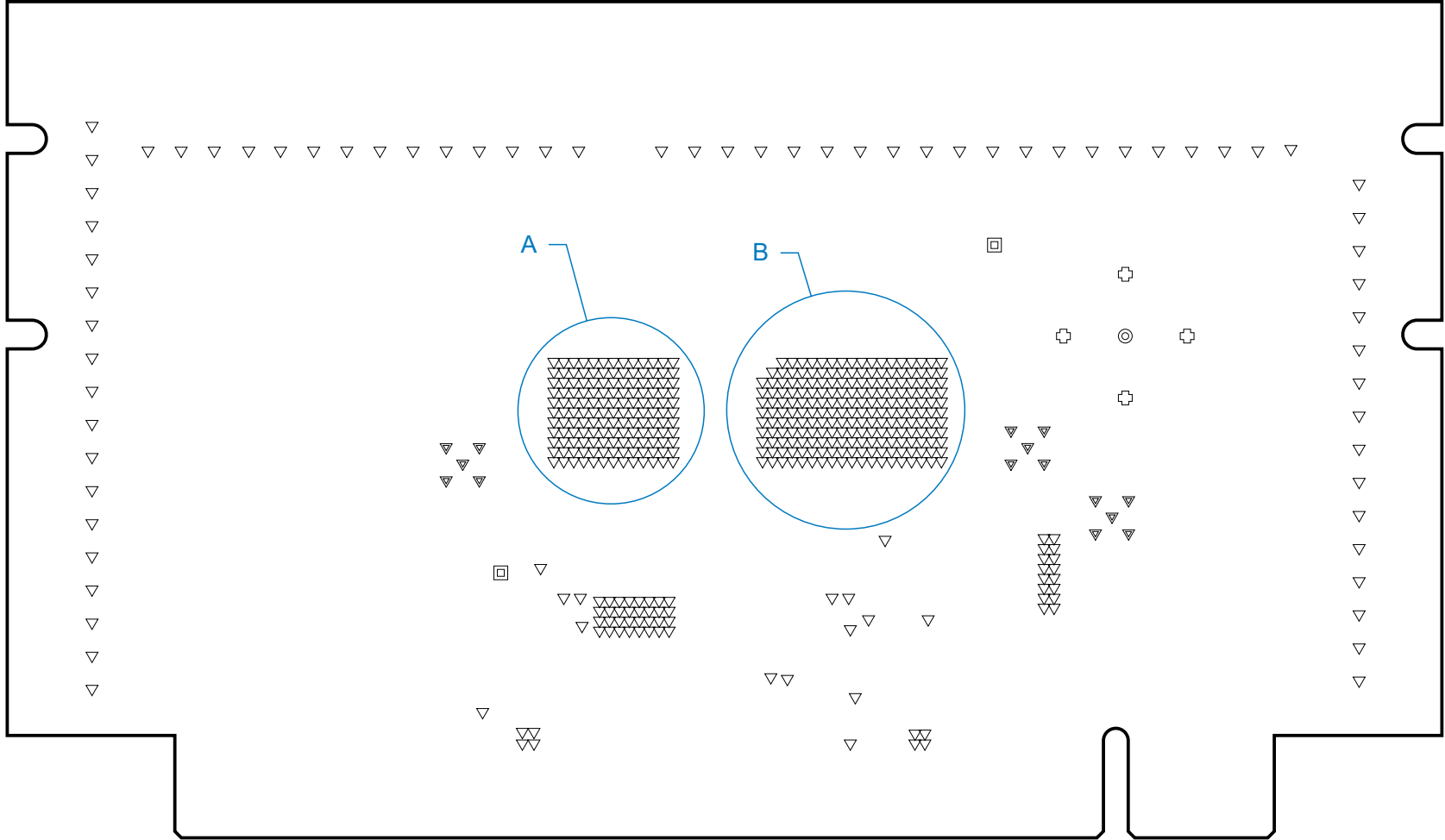
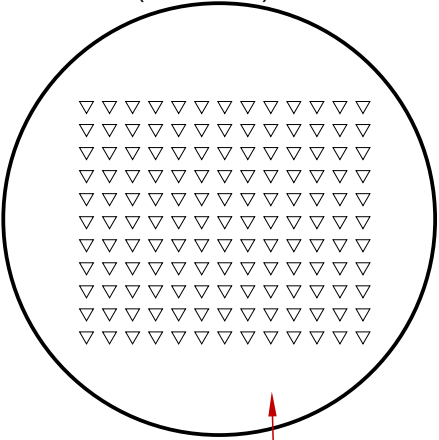


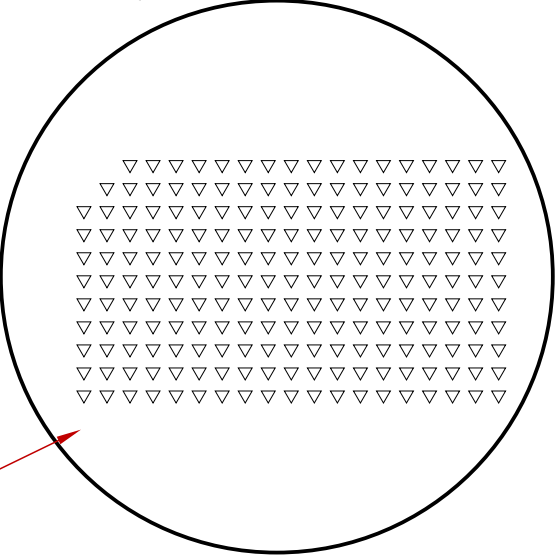
Drill Drawing View (Scale 2:1)



DETAIL A (Scale 4:1)





DETAIL B (Scale 4:1)



Notes:

1. Fabricate per IPC 6012 Class II
2. Material: FR4 equivalent.  
Tg>=170°
3. Cu weight all layers: 4 oz.
4. Total board thickness after plating: 0.062 +/- 8%
5. Final finish: ENIG
6. Soldermask both sides using photo-imagable process. Color: green
7. Silkscreen both sides using non-conductive ink. Color : white
8. All holes to be +/- 0.003 unless otherwise specified. Hole sizes are given after plating. Plated thru-hole shall have a min of 0.002 Cu internal plating.
9. Remove all burrs and sharp edges 0.015 min.
10. Surface finish: ENIG

 Thermal vias in Deatils 'A' and 'B' are to be filled with SAN-EI PHP-900 Epoxy prior to plating. All other vias are tented.

 No gold fingers required.

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
Surface Material	Top Overlay			Legend	GTO
CF-006	Top Solder	0.4mil	Solder Resist	Solder Mask	GTS
Core	TOP	5.5mil		Signal	GTL
CF-006	INNER1	10.0mil	Core-028	Dielectric	
Core		5.5mil		Signal	G1
CF-006	INNER2	21.0mil	Core-037	Dielectric	
Core		5.5mil		Signal	G2
CF-006	BOTTOM	10.0mil	Core-028	Dielectric	
Surface Material	Bottom Solder	5.5mil		Signal	GBL
	Bottom Overlay	0.4mil	Solder Resist	Solder Mask	GBS
				Legend	GBO

Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
▽	488	12.0mil	Plated	
▽	15	33.1mil	Plated	
◎	1	45.0mil	Plated	
⊕	4	70.0mil	Plated	
□	2	125.0mil	Non-Plated	
	510 Total			



Title: J1 HB Edge Card Daughter

Drawing No: MOD-PWR-MM-J1-J1

Date: Mar. 2023

Size: B

Revision: 3.1

Sheet: 1 of 3



Title: J1 HB Edge Card Daughter				
Drawing No: MOD-PWR-MM-J1-J1				
Date: Mar. 2023	Size: B	Revision: 3.1	Sheet: 2	of 3

